

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L²-π-MOSV)

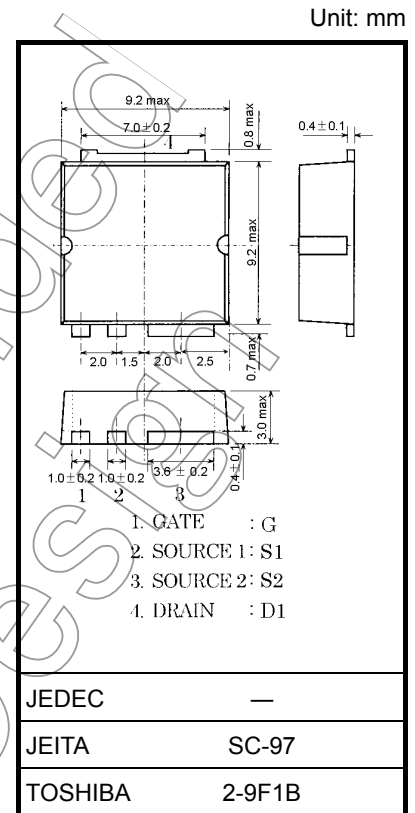
2SK3387

Switching Regulator, DC-DC Converter and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON resistance: $R_{DS(ON)} = 0.08 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 17 S$ (typ.)
- Low leakage current: $I_{DSS} = 100 \mu A$ ($V_{DS} = 150 V$)
- Enhancement mode: $V_{th} = 0.8 \sim 2.0 V$ ($V_{DS} = 10 V, I_D = 1 mA$)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	150	V
Drain-gate voltage ($R_{GS} = 20 k\Omega$)	V_{DGR}	150	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current	DC (Note 1)	I_D	18
	Pulse (Note 1)	I_{DP}	54
Drain power dissipation ($T_c = 25^\circ C$)	P_D	100	W
Single pulse avalanche energy (Note 2)	E_{AS}	176	mJ
Avalanche current	I_{AR}	18	A
Repetitive avalanche energy (Note 3)	E_{AR}	10	mJ
Channel temperature	T_{ch}	150	°C
Storage temperature range	T_{stg}	-55~150	°C



Weight: 0.74 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	1.25	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

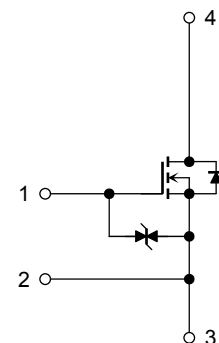
Note 2: $V_{DD} = 50 V, T_{ch} = 25^\circ C$ (initial), $L = 800 \mu H, R_G = 25 \Omega, I_{AR} = 18 A$

Note 3: Repetitive rating: pulse width limited by max junction temperature

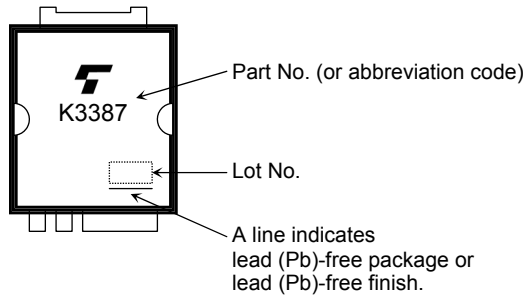
This transistor is an electrostatic-sensitive device.
Please handle with caution.

Notice:

Please use the S1 pin for gate input signal return. Make sure that the main current flows into S2 pin.



Marking



Electrical Characteristics (Note 4) (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Drain cut-off current		I_{DSS}	$V_{DS} = 150\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	150	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	0.8	—	2.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 4\text{ V}, I_D = 9\text{ A}$	—	0.09	0.18	Ω
			$V_{GS} = 10\text{ V}, I_D = 9\text{ A}$	—	0.08	0.12	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 9\text{ A}$	10	17	—	S
Input capacitance		C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	1380	—	pF
Reverse transfer capacitance		C_{rss}		—	200	—	
Output capacitance		C_{oss}		—	610	—	
Switching time	Rise time	t_r		—	12	—	ns
	Turn-on time	t_{on}		—	20	—	
	Fall time	t_f		—	12	—	
	Turn-off time	t_{off}		Duty $\leq 1\%$, $t_w = 10\ \mu\text{s}$	—	68	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} = 120\text{ V}, V_{GS} = 10\text{ V}, I_D = 18\text{ A}$	—	57	—	nC
Gate-source charge		Q_{gs}		—	43	—	nC
Gate-drain ("miller") charge		Q_{gd}		—	14	—	nC

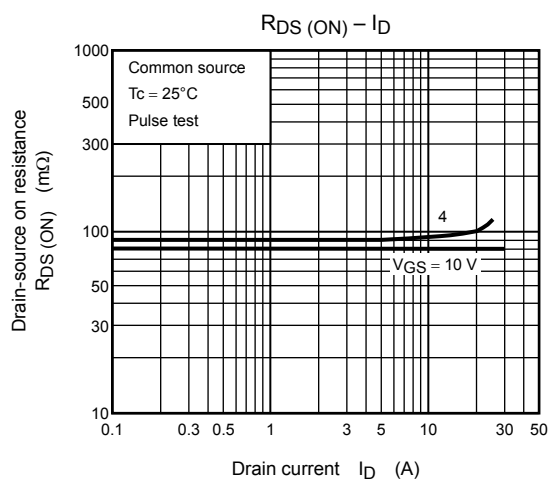
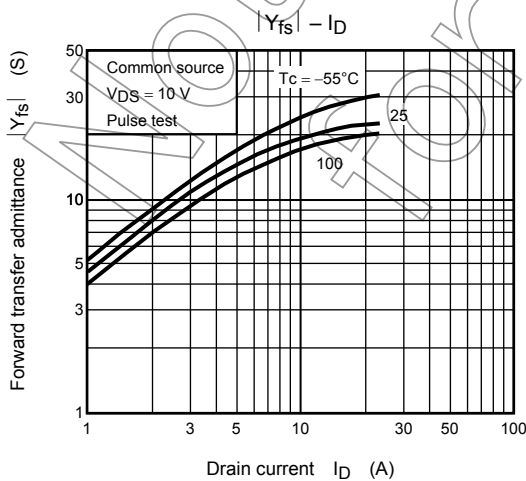
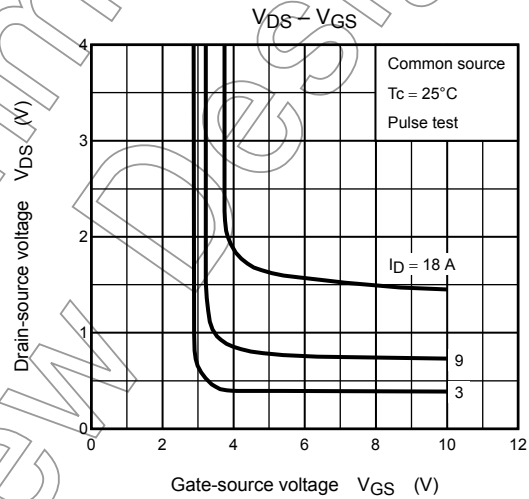
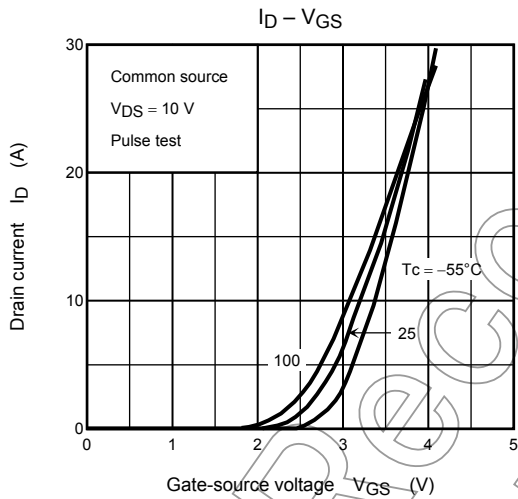
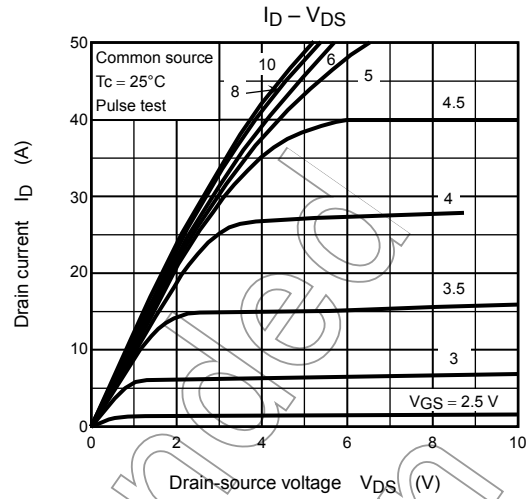
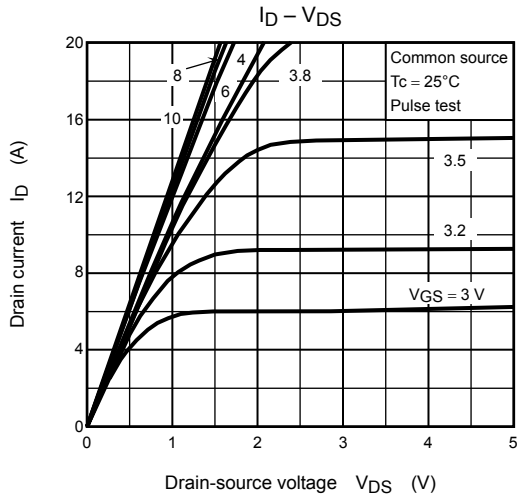
Note 4: Connect the S1 and S2 pins together, and ground them except during switching time measurement.

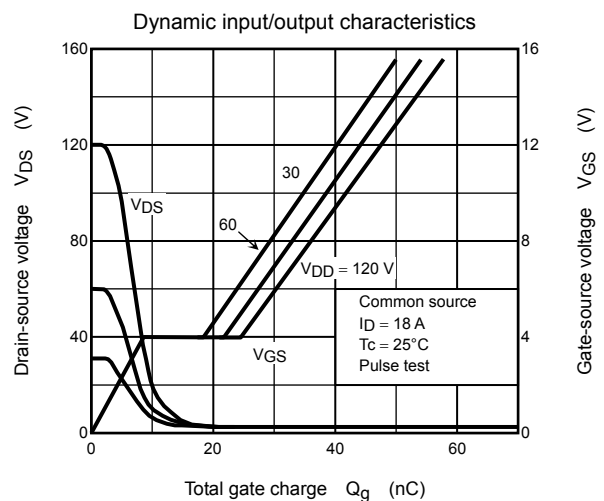
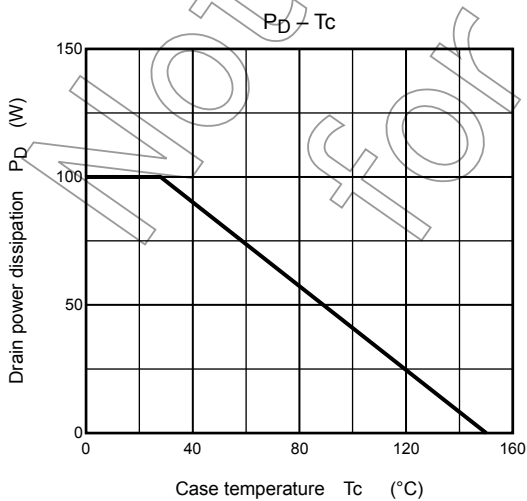
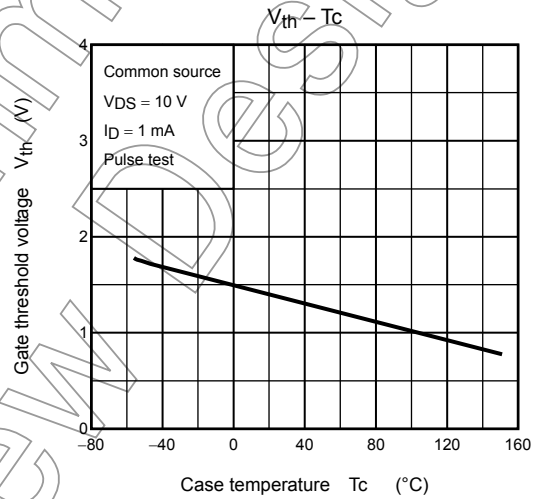
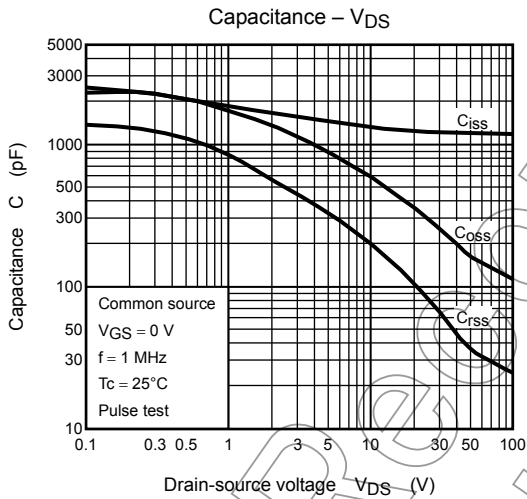
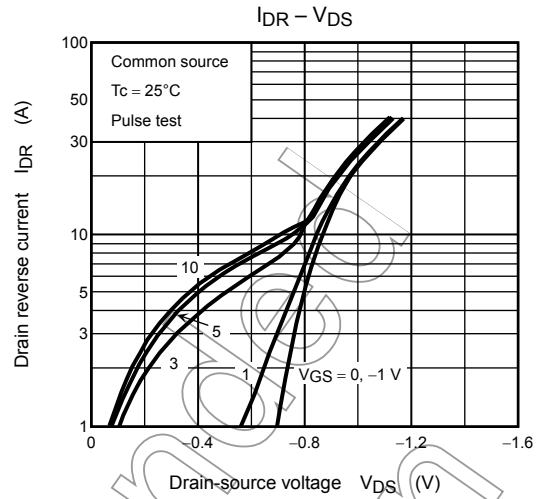
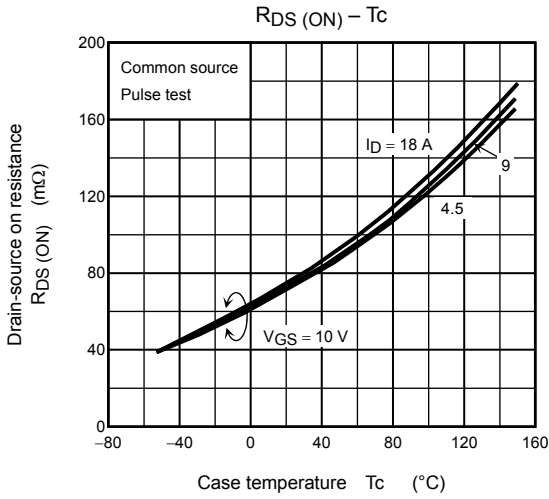
Source-Drain Diode Ratings and Characteristics (Note 5) (Ta = 25°C)

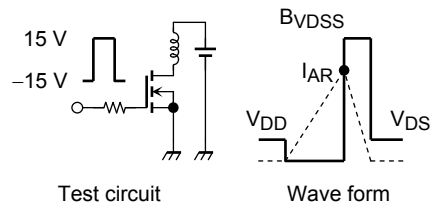
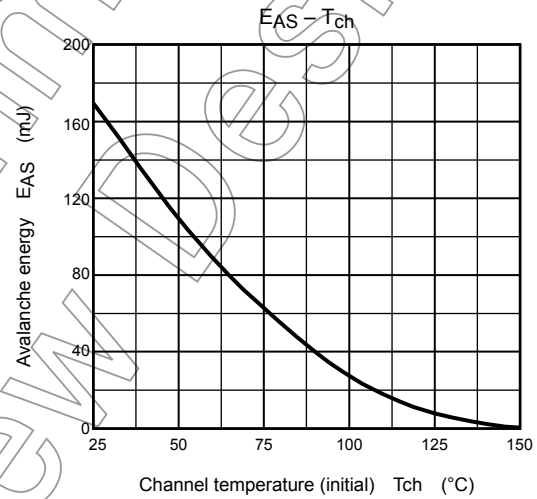
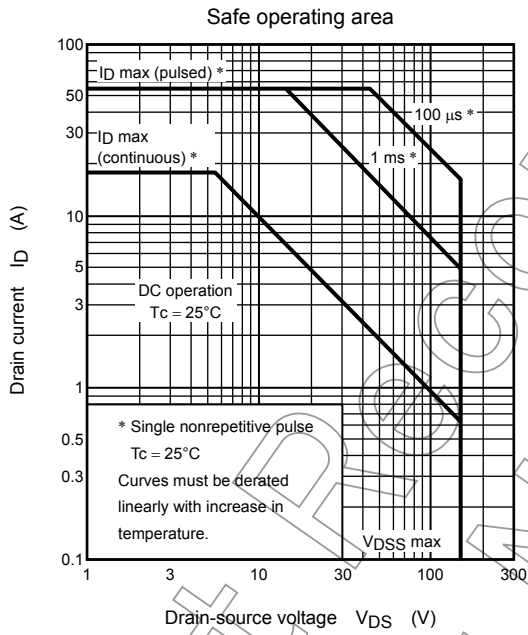
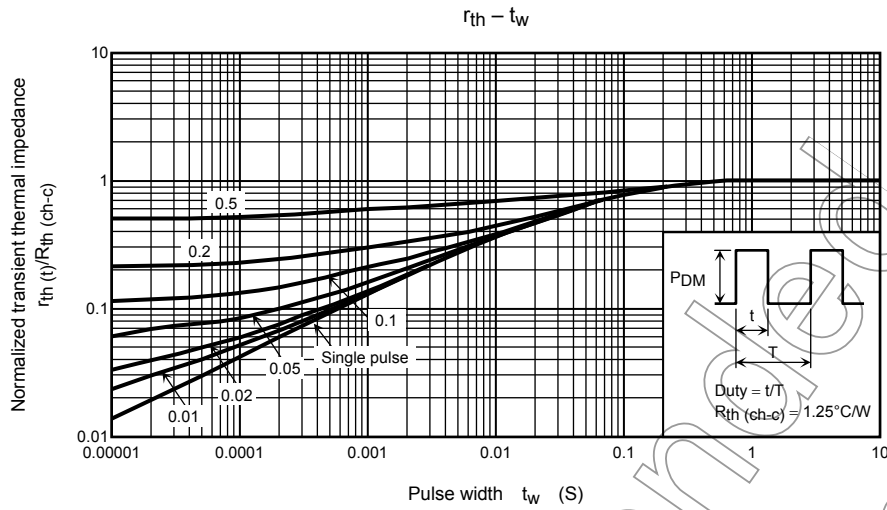
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1, 5)	I_{DR1}	—	—	—	18	A
Pulse drain reverse current (Note 1, 5)	I_{DRP1}	—	—	—	54	A
Continuous drain reverse current (Note 1, 5)	I_{DR2}	—	—	—	1	A
Pulse drain reverse current (Note 1, 5)	I_{DRP2}	—	—	—	4	A
Diode forward voltage	V_{DS2F}	$I_{DR1} = 18\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.7	V
Reverse recovery time	t_{rr}	$I_{DR} = 18\text{ A}, V_{GS} = 0\text{ V},$	—	185	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR}/dt = 100\text{ A}/\mu\text{s}$	—	1.3	—	μC

Note 5: I_{DR1}, I_{DRP1} : Current flowing between the drain and the S2 pin. Ensure that the S1 pin is left open.
 I_{DR2}, I_{DRP2} : Current flowing between the drain and the S1 pin. Ensure that the S2 pin is left open.

Unless otherwise specified, connect the S1 and S2 pins together, and ground them







$R_G = 25 \Omega$
 $V_{DD} = 50 V, L = 0.8 mH$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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